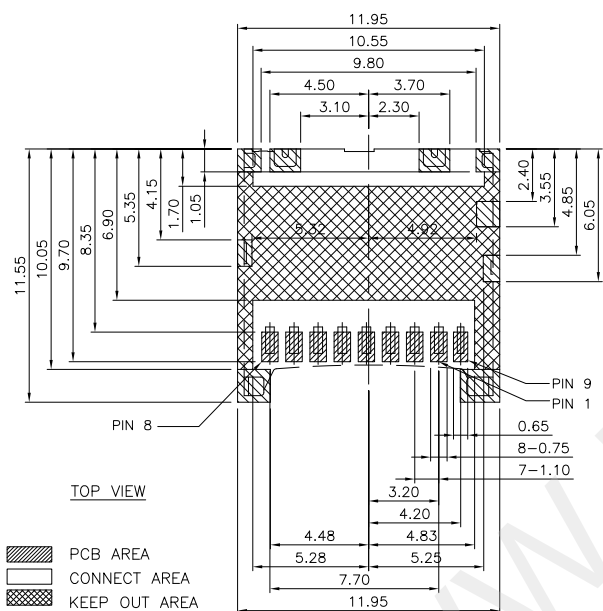
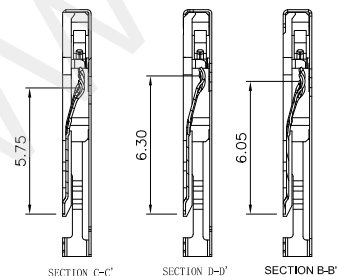
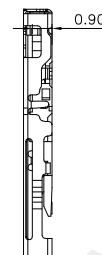
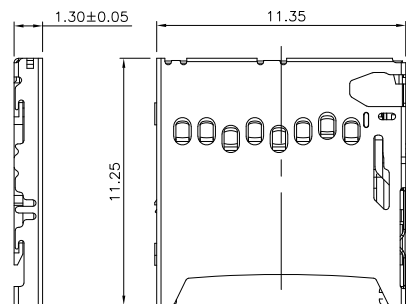
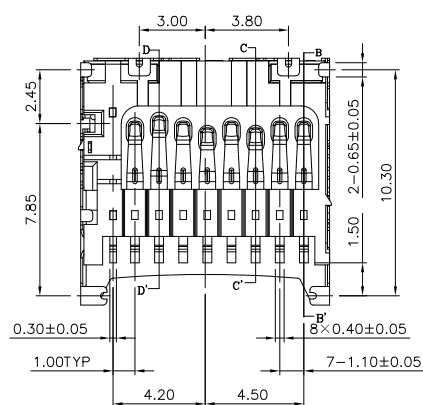
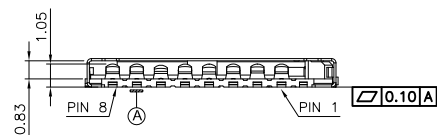
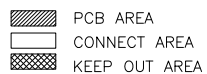




TOP VIEW

RECOMMEND PCB LAYOUT
TOLERANCE: ±0.05

MICRO SD	
PIN1	DAT2
PIN2	CD/DAT3
PIN3	CMD
PIN4	VDD
PIN5	CLK
PIN6	VSS
PIN7	DAT0
PIN8	DAT1
PIN9	CD

MATERIALS

1. HOUSING :THERMOPLASTIC (UL 94V-0).
2. TERMINAL : COPPER ALLOY, PLATING SEE TABLE.
3. SHELL : SUS.

FINISH :

CONTACT: Au 1u" PLATED ON CONTACT AREA ;
GOLD FLASH PLATING ON SOLDER TAILS , WITH
ENTIRE CONTACT UNDERPLATED 50u"Min . NICKEL
SHELL: 30u"Min. NICKEL UNDERPLATED OVERALL ,
GOLD FLASH PLATED ON SOLDER TAILS

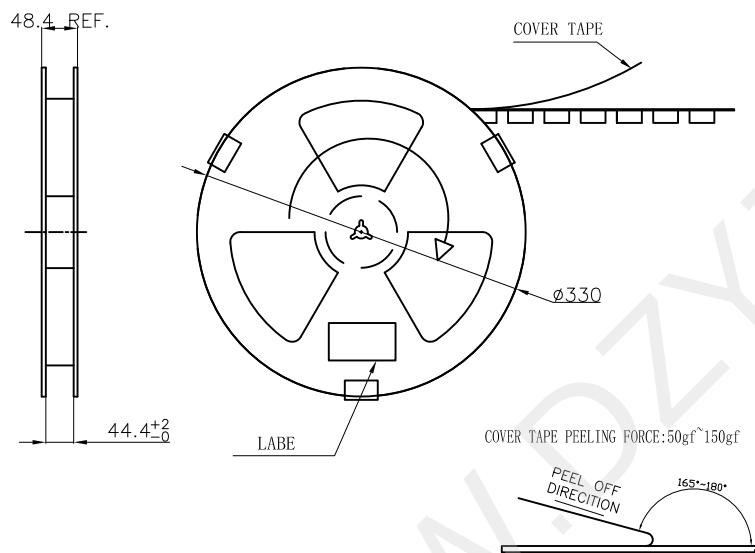
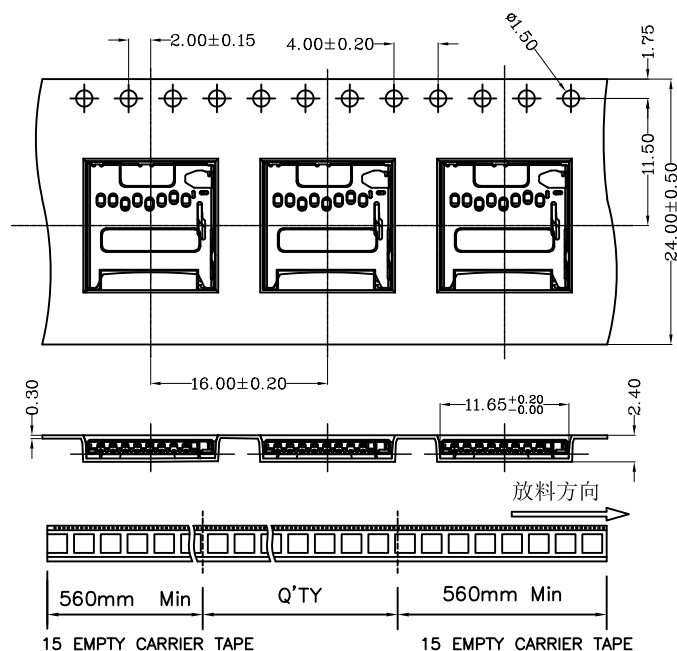
SPECIFICATION

1. CURRENT RATING : 0.5 A. MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR 1 MINUTE.
3. INSULATION RESISTANCE : 1000MQ MIN.AT 500V DC.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING LIFE: 3000 CYCLES.
6. OPERATING TEMPERATURE : -40°C TO +85°C.
7. CIRCUIT DIAGRAM FOR CARD DETECT SWITCH
CARD DETECT SWITCH (PIN 9)



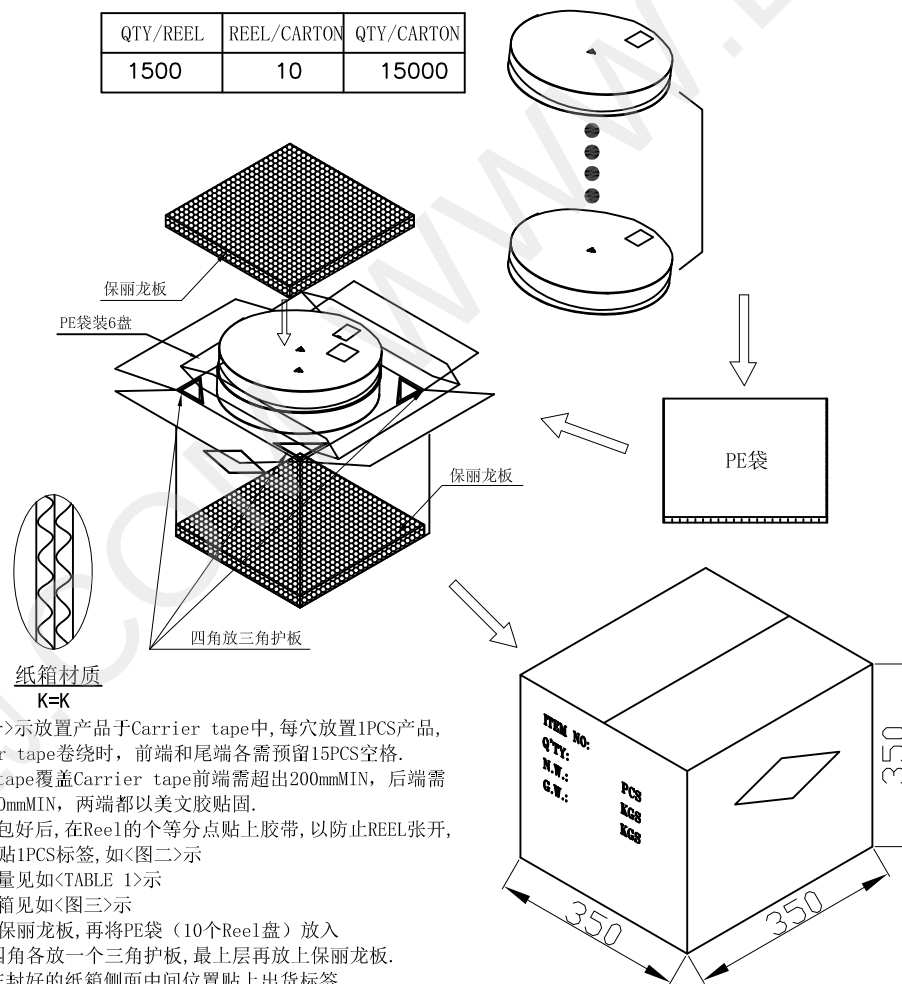
深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF内焊 NO PUSH 1.3H 无侦测P	
 UNIT: mm [inch]		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC194-TF09-130
		APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
				DRAW NO:	HYC-2608241828
				SHEET NO.	1 OF 1



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1500	10	15000



备注:

1. 依<图一>示放置产品于Carrier tape中, 每穴放置1PCS产品, Carrier tape卷绕时, 前端和尾端各需预留15PCS空格.
2. Cover tape覆盖Carrier tape前端需超出200mmMIN, 后端需留出300mmMIN, 两端都以美文胶贴固.
3. 包装机包好后, 在Reel的个等分点贴上胶带, 以防止REEL张开, 每Reel贴1PCS标签, 如<图二>示
4. 包装数量见如<TABLE 1>示
5. 包装成箱见如<图三>示
箱底放保丽龙板, 再将PE袋(10个Reel盘)放入箱内, 四角各放一个三角护板, 最上层再放上保丽龙板.
6. 封箱, 在封好的纸箱侧面中间位置贴上出货标签.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	
			SHEET NO.	1 OF 1